REMARKS/ARGUMENTS

Reconsideration of the application is requested.

Claims 1-2, 4-5, and 9-11 remain in the application. Claim 1 has been amended. Claims 3 and 6-8 have been cancelled.

In the section entitled "Claim Rejections - 35 USC § 102" on pages 2-4 of the above-mentioned Office action, claims 1-11 have been rejected as being anticipated by Buican et al. (US Pat. No. 6,339,536) under 35 U.S.C. § 102(b).

The rejection has been noted and claim 1 has been amended in an effort to even more clearly define the invention of the instant application. Support for the changes is found in original claims 3 and 6-8.

Before discussing the prior art in detail, it is believed that a brief review of the invention as claimed, would be helpful.

Claim 1 calls for, inter alia:

> a sealing layer disposed between said I/O shield and the housing, said sealing layer sealing said housing aperture and forming an electrical contact with said wall surfaces of said housing aperture, said sealing layer including readily malleable electrically conductive material.

Buican et al. disclose a gasket 310 made of an electrically conductive form or, in a preferred embodiment, a gasket made of a nickel-woven mesh. The gasket 310 is positioned to electrically contact the interior side of the IO shield 307. Therefore, Buican et al. disclose a sealing layer that forms an electrical contact between the IO shield and IO connectors, but not between the IO shield and the housing.

In contrast, according to amended claim 1 of the instant application, the sealing layer (2) is disposed between the I/O shield (1) and the housing (8). It is noted that the wavelength of electromagnetic fields, which has to be considered, is now much shorter than in 1999 when Buican et al. filed their patent application. This is because of an increasing frequency of microprocessor processing rates, up to 1 GHz and more. It would not be enough to have planar metallized surfaces to be in electrical contact to avoid these electromagnetic influences. It has to be ensured that the electric contact is nearly 100% over the whole surface of the tubular planar metallized surfaces. It is one of the major advantages of the invention of the instant application that the sealing forms an electrical contact between the housing and the IO shield and also the IO connectors.

In addition, the material used by Buican et al. for the gasket is not easily or readily malleable, as recited in amended claim 1 of the instant application.

Clearly, Buican et al. do not show "a sealing layer disposed between said I/O shield and the housing, said sealing layer sealing said housing aperture and forming an electrical contact with said wall surfaces of said housing aperture, said sealing layer including readily malleable electrically conductive material," as recited in claim 1 of the instant application.

Claim 1 is, therefore, believed to be patentable over Buican et al. and since all of the dependent claims are dependent on claim 1, they are believed to be patentable as well.

In view of the foregoing, reconsideration and allowance of claims 1-2, 4-5, and 9-11 are solicited.

In the event the Examiner should still find any of the claims to be unpatentable, counsel would appreciate a telephone call so that, if possible, patentable language can be worked out.

If an extension of time for this paper is required, petition for extension is herewith made. Please charge any fees which

might be due with respect to 37 CFR Sections 1.16 and 1.17 to the Deposit Account of Lerner and Greenberg, P.A., No. 12-1099.

Respectfully submitted,

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YC

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